# Low V<sub>CE(sat)</sub> Transistor, PNP, 60 V, 6.0 A, SOT-223 Package

ON Semiconductor's e<sup>2</sup>PowerEdge family of low  $V_{CE(sat)}$  transistors are surface mount devices featuring ultra low saturation voltage ( $V_{CE(sat)}$ ) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical applications are DC–DC converters and power management in portable and battery powered products such as cellular and cordless phones, PDAs, computers, printers, digital cameras and MP3 players. Other applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e<sup>2</sup>PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

#### Features

- Complementary to NSS60601MZ4
- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant\*

Rating	Symbol	Max	Unit		
Collector-Emitter Voltage	V <sub>CEO</sub>	-60	Vdc		
Collector-Base Voltage	V <sub>CBO</sub>	-100	Vdc		
Emitter-Base Voltage	V <sub>EBO</sub>	-6.0	Vdc		
Collector Current – Continuous	۱ <sub>C</sub>	-6.0	А		
Collector Current – Peak	I <sub>CM</sub>	-12.0	А		

## **MAXIMUM RATINGS** ( $T_A = 25^{\circ}C$ )

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

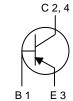


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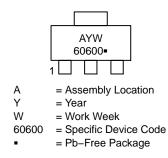
#### www.onsemi.com

-60 VOLTS, 6.0 AMPS 2.0 WATTS PNP LOW  $V_{CE(sat)}$  TRANSISTOR EQUIVALENT  $R_{DS(on)}$  50 m $\Omega$ 

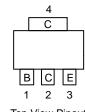




#### MARKING DIAGRAM



#### **PIN ASSIGNMENT**



**Top View Pinout** 

ORDERING INFORMATION

\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

# THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation $T_A = 25^{\circ}C$ Derate above $25^{\circ}C$	P <sub>D</sub> (Note 1)	800 6.5	mW mW/°C
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub> (Note 1)	155	°C/W
Total Device Dissipation $T_A = 25^{\circ}C$ Derate above $25^{\circ}C$	P <sub>D</sub> (Note 2)	2 15.6	W mW/°C
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub> (Note 2)	64	°C/W
Total Device Dissipation (Single Pulse < 10 sec.)	P <sub>Dsingle</sub> (Note 3)	710	mW
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

FR-4 @ 7.6 mm<sup>2</sup>, 1 oz. copper traces.
FR-4 @ 645 mm<sup>2</sup>, 1 oz. copper traces.
Thermal response.

## **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NSS60600MZ4T1G	SOT-223 (Pb-Free)	1,000 / Tape & Reel
NSV60600MZ4T1G	SOT-223 (Pb-Free)	1,000 / Tape & Reel
NSS60600MZ4T3G	SOT-223 (Pb-Free)	4,000 / Tape & Reel
NSV60600MZ4T3G	SOT-223 (Pb-Free)	4,000 / Tape & Reel

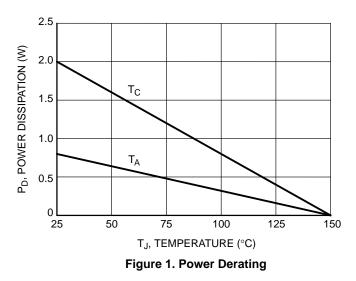
+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

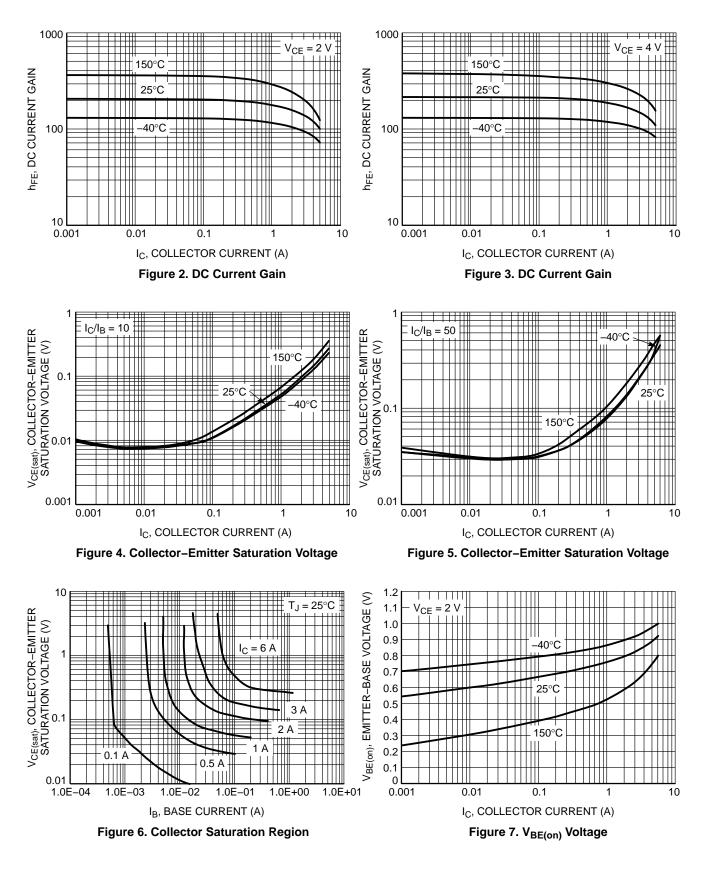
Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS	·				
Collector – Emitter Breakdown Voltage ( $I_C = -10$ mAdc, $I_B = 0$ )	V <sub>(BR)CEO</sub>	-60	-	_	Vdc
Collector – Base Breakdown Voltage ( $I_C = -0.1 \text{ mAdc}, I_E = 0$ )	V <sub>(BR)CBO</sub>	-100	-	-	Vdc
Emitter-Base Breakdown Voltage ( $I_E = -0.1 \text{ mAdc}, I_C = 0$ )	V <sub>(BR)EBO</sub>	-6.0	-	-	Vdc
Collector Cutoff Current ( $V_{CB} = -100$ Vdc, $I_E = 0$ )	I <sub>CBO</sub>	-	-	-0.1	μAdc
Emitter Cutoff Current (V <sub>EB</sub> = -6.0 Vdc)	I <sub>EBO</sub>	_	-	-0.1	μAdc
ON CHARACTERISTICS					
DC Current Gain (Note 4) ( $I_C = -500 \text{ mA}, V_{CE} = -2.0 \text{ V}$ ) ( $I_C = -1.0 \text{ A}, V_{CE} = -2.0 \text{ V}$ ) ( $I_C = -2.0 \text{ A}, V_{CE} = -2.0 \text{ V}$ ) ( $I_C = -6.0 \text{ A}, V_{CE} = -2.0 \text{ V}$ )	h <sub>FE</sub>	150 120 100 70		_ 360 _ _	_
Collector – Emitter Saturation Voltage (Note 4) ( $I_C = -0.1 \text{ A}, I_B = -2.0 \text{ mA}$ ) ( $I_C = -1.0 \text{ A}, I_B = -0.100 \text{ A}$ ) ( $I_C = -2.0 \text{ A}, I_B = -0.200 \text{ A}$ ) ( $I_C = -3.0 \text{ A}, I_B = -60 \text{ mA}$ ) ( $I_C = -6.0 \text{ A}, I_B = -0.6 \text{ A}$ )	V <sub>CE(sat)</sub>	- - - -	 0.050 	-0.050 -0.070 -0.120 -0.250 -0.350	V
Base – Emitter Saturation Voltage (Note 4) ( $I_C = -1.0 \text{ A}, I_B = -0.1 \text{ A}$ )	V <sub>BE(sat)</sub>	_	_	-1.0	V
Base – Emitter Turn–on Voltage (Note 4) ( $I_C = -1.0 \text{ A}, V_{CE} = -2.0 \text{ V}$ )	V <sub>BE(on)</sub>	_	_	-0.900	V
Cutoff Frequency ( $I_C = -500$ mA, $V_{CE} = -10$ V, f = 1.0 MHz)	f <sub>T</sub>	100	_	-	MHz
Input Capacitance (V <sub>EB</sub> = 5.0 V, f = 1.0 MHz)	Cibo	_	360	_	pF
Output Capacitance (V <sub>CB</sub> = 10 V, f = 1.0 MHz)	Cobo	-	60	-	pF
SWITCHING CHARACTERISTICS			•		
Delay (V <sub>CC</sub> = -30 V, I <sub>C</sub> = 750 mA, I <sub>B1</sub> = 15 mA)	t <sub>d</sub>	-	100	-	ns
Rise ( $V_{CC} = -30 \text{ V}, \text{ I}_{C} = 750 \text{ mA}, \text{ I}_{B1} = 15 \text{ mA}$ )	t <sub>r</sub>	_	180	-	ns
Storage (V <sub>CC</sub> = $-30$ V, I <sub>C</sub> = 750 mA, I <sub>B1</sub> = 15 mA)	t <sub>s</sub>	-	540	-	ns
Fall (V <sub>CC</sub> = –30 V, I <sub>C</sub> = 750 mA, I <sub>B1</sub> = 15 mA)	t <sub>f</sub>	_	145	-	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

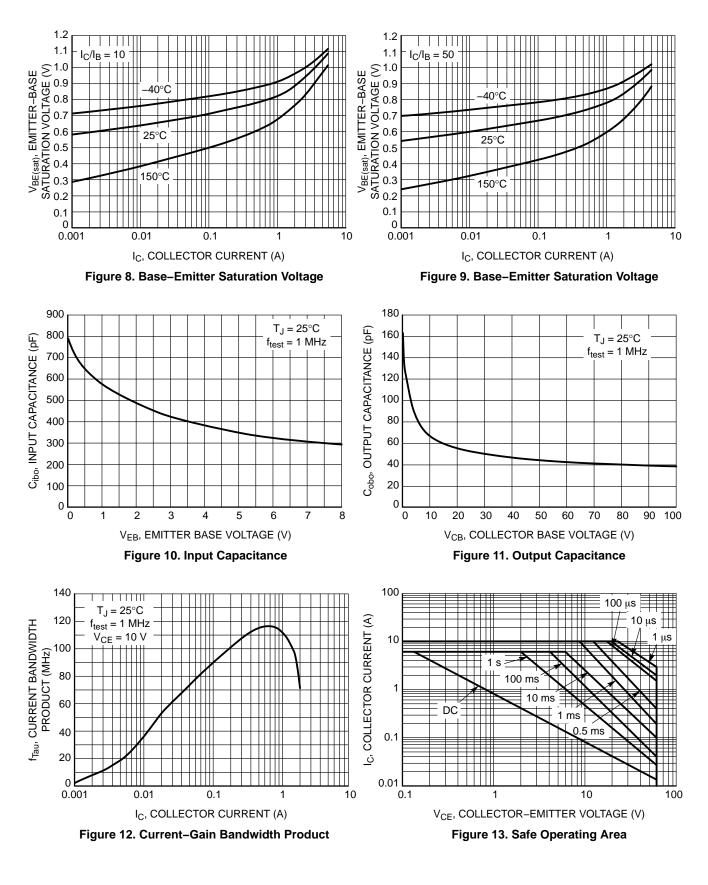
4. Pulsed Condition: Pulse Width = 300 msec, Duty Cycle  $\leq$  2%.



# **TYPICAL CHARACTERISTICS**



# **TYPICAL CHARACTERISTICS**



DATE 02 OCT 2018

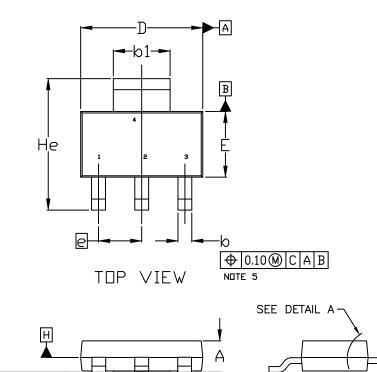




SCALE 1:1

0.10 C

A1



-11

SIDE VIEW

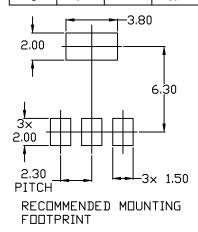
DETAIL A

NDTES:

SOT-223 (TO-261) CASE 318E-04 ISSUE R

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. DIMENSIONS D & E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.200MM PER SIDE.
- 4. DATUMS A AND B ARE DETERMINED AT DATUM H.
- 5. ALLS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST PDINT OF THE PACKAGE BODY.
- 6. POSITIONAL TOLERANCE APPLIES TO DIMENSIONS 6 AND 61.

	MILLIMETERS			
DIM	MIN.	NDM.	MAX.	
A	1.50	1.63	1.75	
A1	0.02	0.06	0.10	
b	0.60	0.75	0.89	
b1	2.90	3.06	3.20	
с	0.24	0.29	0.35	
D	6.30	6.50	6.70	
E	3.30	3.50	3.70	
e	2.30 BSC			
L	0.20			
L1	1.50	1.75	2.00	
He	6.70	7.00	7.30	
θ	0*		10*	



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FRONT VIEW

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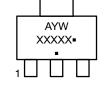
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#### SOT-223 (TO-261) CASE 318E-04 ISSUE R

## DATE 02 OCT 2018

STYLE 1: PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR	STYLE 2: PIN 1. ANODE 2. CATHODE 3. NC 4. CATHODE	STYLE 3: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN	STYLE 4: PIN 1. SOURCE 2. DRAIN 3. GATE 4. DRAIN	STYLE 5: PIN 1. DRAIN 2. GATE 3. SOURCE 4. GATE
STYLE 6: PIN 1. RETURN 2. INPUT 3. OUTPUT 4. INPUT	STYLE 7: PIN 1. ANODE 1 2. CATHODE 3. ANODE 2 4. CATHODE	STYLE 8: CANCELLED	Style 9: Pin 1. Input 2. Ground 3. Logic 4. Ground	STYLE 10: PIN 1. CATHODE 2. ANODE 3. GATE 4. ANODE
STYLE 11: PIN 1. MT 1 2. MT 2 3. GATE 4. MT 2	Style 12: Pin 1. Input 2. Output 3. NC 4. Output	STYLE 13: PIN 1. GATE 2. COLLECTOR 3. EMITTER 4. COLLECTOR		

# GENERIC MARKING DIAGRAM\*



- A = Assembly Location
- Y = Year
- W = Work Week
- XXXXX = Specific Device Code
- = Pb-Free Package
- (Note: Microdot may be in either location) \*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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